HARP

PC3SD12NTZ Series

V_{DRM}: 600V, Cost effective Non-zero cross type **DIP** 6pin Phototriac Coupler for triggering



Description

PC3SD12NTZ Series Phototriac Coupler include an infrared emitting diode (IRED) optically coupled to an output Phototriac.

These devices feature full wave control and are ideal isolated drivers for medium to high current Triacs.

DIP package provides 5.0kV isolation from input to output with superior commutative noise immunity.

Features

- 1. High repetitive peak off-state voltage (VDRM : 600V)
- 2. Non-zero crossing functionality
- 3. 6 pin DIP package
- 4. Superior noise immunity (dV/dt : MIN. 1 000V/µs)
- 5. Double transfer mold construction (Ideal for Flow Soldering)
- 6. High isolation voltage between input and output $(V_{iso}(rms) : 5.0kV)$

Agency approvals/Compliance

- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. 3SD12)
- 2. Approved by CSA, file No. CA95323 (as model No. 3SD12)
- 3. Optionary available VDE Approved (*)(DIN EN 60747-5-2), file No. 40008189 (as model No. 3SD12)
- 4. Package resin : UL flammability grade (94V-0)
 - (*) DIN EN60747-5-2 : successor standard of DIN VDE0884. Up to Date code "RD" (December 2003), approval of DIN VDF0884 From Date code "S1" (January 2004), approval of DIN EN60747-5-2.
 - (**) Reinforced insulation type is also available. (PC3SF11YVZ Series)

Applications

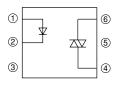
- 1. Triggering for Triacs used to switch on and off devices which require AC Loads. For example heaters, fans, motors, solenoids, and valves.
- 2. Triggering for Triacs used for implementing phase control in applications such as lighting control and temperature control (HVAC).
- 3. AC line control in power supply applications.

Notice The content of data sheet is subject to change without prior notice

In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.



Internal Connection Diagram



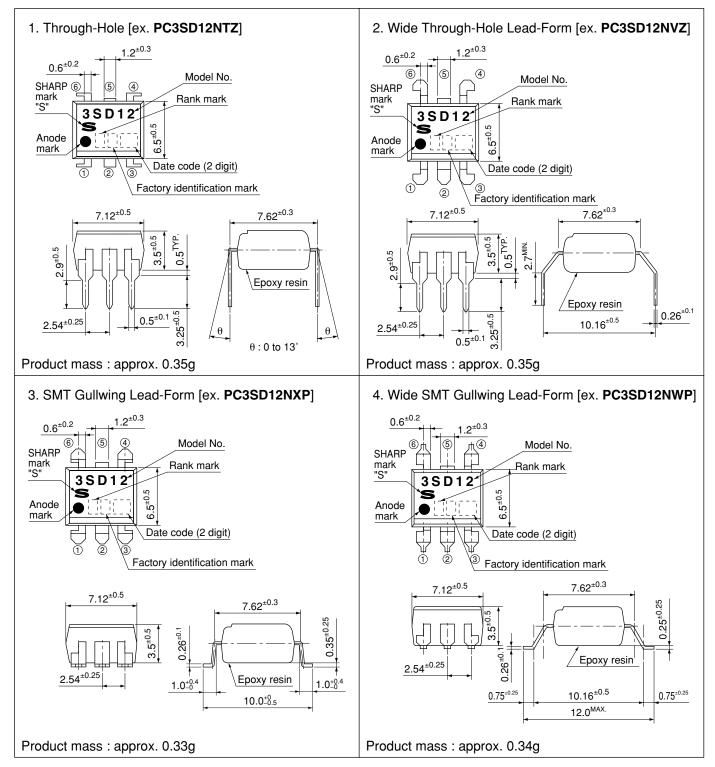


5 No external connection

6 Cathode/Anode

Outline Dimensions

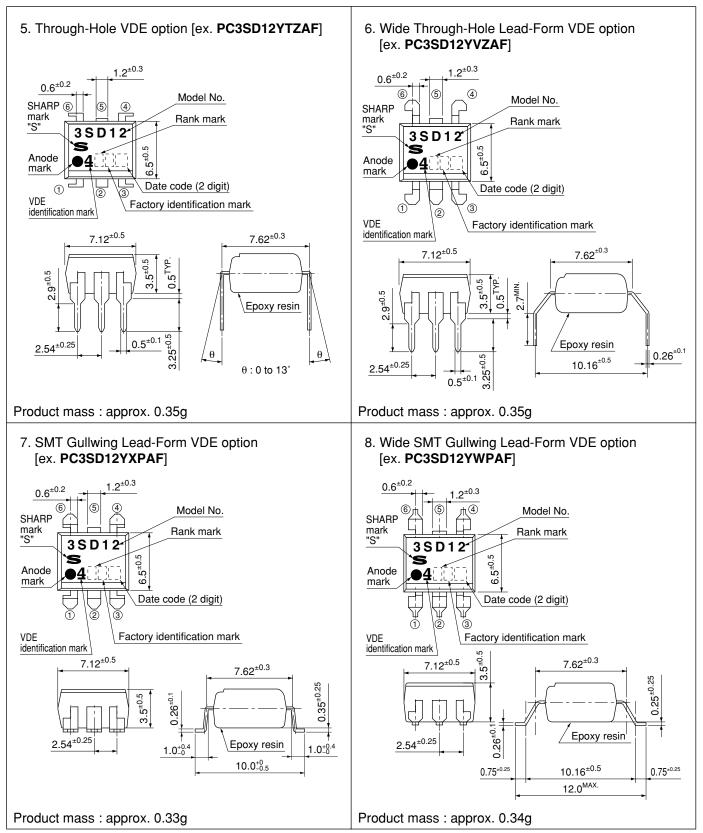
(Unit : mm)





Outline Dimensions





*Pin 5 is not allowed external connection



Date code (2 digit)

	1st o	digit		2nd digit		
	Year of p	roduction		Month of production		
A.D.	Mark	A.D	Mark	Month	Mark	
1990	A	2002	Р	January	1	
1991	В	2003	R	February	2	
1992	C	2004	S	March	3	
1993	D	2005	Т	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	Х	August	8	
1998	K	2010	А	September	9	
1999	L	2011	В	October	0	
2000	М	2012	С	November	N	
2001	N		:	December	D	

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin
no mark	I
	Japan
	Indonesia
\square	Philippines
	China

* This factory marking is for identification purpose only.

Please contact the local SHARP sales representative to see the actural status of the production.

Rank mark

Refer to the Model Line-up table

Absolute Maximum Ratings

Abs	■ Absolute Maximum Ratings (T _a =25°C							
	Parameter	Symbol	Rating	Unit				
Forward current		I_F	50	mA				
Input	Reverse voltage	V _R	6	V				
	RMS ON-state current	I _T (rms)	0.1	А				
Output	Peak one cycle surge current	I _{surge}	1.2 *3	А				
	Repetitive peak OFF-state voltage		600	V				
^{*1} Isolatic	on voltage	V _{iso} (rms)	5.0	kV				
	ing temperature	T _{opr}	-30 to +100	°C				
Storage	e temperature	T _{stg}	-55 to +125	°C				
*2Solderi	ng temperature	T _{sol}	270^{*4}	°C				

*1 40 to 60%RH, AC for 1minute, f=60Hz *2 For 10s *3 f=50Hz sine wave

*4 Lead solder plating models: 260°C

Electro-optical Characteristics

Soldering area

1mm

Elec	ctro-optical Characte	eristics					(T	$T_a=25^{\circ}C)$
	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Innut	Forward voltage		V _F	I _F =20mA	-	1.2	1.4	V
Input	Reverse current		I _R	$V_R=3V$	-	-	10	μΑ
	Repentitive peak OFF-state	current	I _{DRM}	$V_D = V_{DRM}$	_	-	1	μΑ
0 ()	ON-state voltage		VT	I _T =0.1A	_	-	2.5	V
Output	Holding current		I _H	V _D =6V	0.1	-	3.5	mA
	Critical rate of rise of OFF-state voltage		dV/dt	$V_D = 1/\sqrt{2} \cdot V_{DRM}$	1 000	2 000	-	V/µs
Transfer	Minimum trigger current	Rank A	I _{FT}	$V_D=6V, R_L=100\Omega$	-	-	10	mA
charac-	Isolation resistance		R _{ISO}	DC500V,40 to 60%RH	5×10 ¹⁰	1011	-	Ω
teristics	Turn-on time		t _{on}	$V_{\rm D}=6V, R_{\rm L}=100\Omega, I_{\rm F}=20mA$	_	_	50	μs



■ Model Line-up

Lead Form	Throug	gh-Hole SMT Gullwing Wide Through-Hole							
Shipping Packag	e	Sleeve 50pcs/sleeve					Rank mark	I _{FT} [mA] (V _D =6V,	
DIN EN60747-5-2		Approved		Approved		Approved		$R_{L}=100\Omega$)	
Model No.	PC3SD12NTZAF	PC3SD12YTZAF	PC3SD12NXZAF	PC3SD12YXZAF	PC3SD12NVZAF	PC3SD12YVZAF	A	MAX. 10	
Lead Form	Wide SMT	Gullwing	SMT Gu	llwing	Wide SMT	Gullwing			
		eve		Ta	ping			I _{FT} [mA]	
Shipping Packag	50pcs/sleeve		1 000pcs/reel			Rank mark	$(V_D = 6V)$		
DIN EN60747-5-2		Approved		Approved		Approved		$R_{L}=100\Omega$)	
Model No.	PC3SD12NWZAF	PC3SD12YWZAF	PC3SD12NXPAF	PC3SD12YXPAF	PC3SD12NWPAF	PC3SD12YWPAF	A	MAX. 10	

Please contact a local SHARP sales representative to inquire about production status.

Fig.1 Forward Current vs. Ambient Temperature

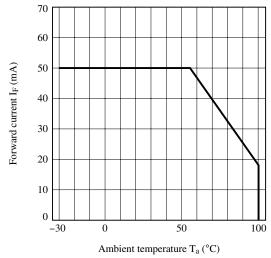
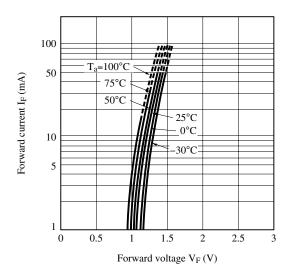


Fig.3 Forward Current vs. Forward Voltage





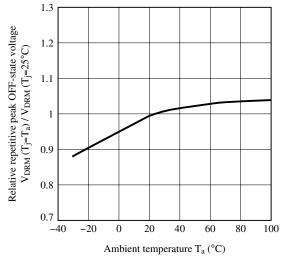


Fig.2 RMS ON-state Current vs. Ambient Temperature

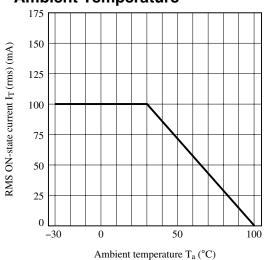


Fig.4 Minimum Trigger Current vs. Ambient Temperature

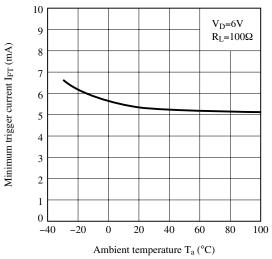


Fig.6 ON-state Voltage vs. Ambient Temperature

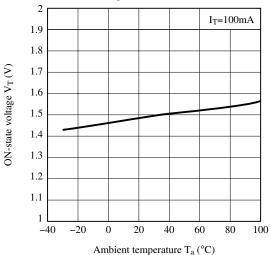




Fig.7 Holding Current vs. Ambient Temperature

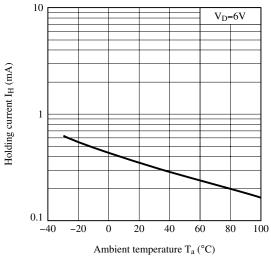
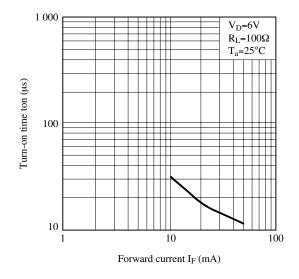
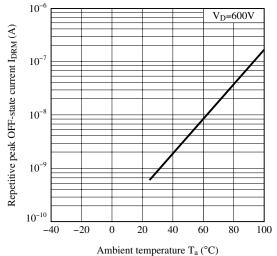


Fig.9 Turn-on Time vs. Forward Current



Remarks : Please be aware that all data in the graph are just for reference.

Fig.8 Repetitive Peak OFF-state Current vs. Ambient Temperature



Sheet No.: D2-A07701FEN



Design Considerations

Design guide

In order for the Phototriac to turn off, the triggering current (I_F) must be 0.1mA or less.

Please refrain from using these devices in a direct drive configuration.

These Phototriac Coupler are intended to be used as triggering device for main Triacs.

Please ensure that the output rating of these devices will be sufficient for triggering the main output Triac of your choice. Failure to do may result in malfunctions.

In phase control applications or where the Phototriac Coupler is being by a pulse signal, please ensure that the pulse width is a minimum of 1ms.

For designs that will experience excessive noise or sudden changes in load voltage, please include an appropriate snubber circuit as shown in the below circuit.

Please keep in mind that Sharp Phototriac Couplers incorporate superor dV/dt ratings which can often eliminate the need for a snubber circuit.

Degradation

In general, the emission of the IRED used in Phototriac Couplers will degrade over time. In the case where long term operation and / or constant extreme temperature fluctuations will be applied to

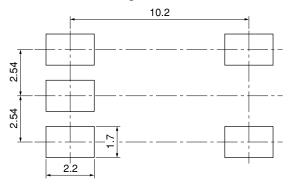
the devices, please allow for a worst case scenario of 50% degradation over 5years.

Therefore in order to maintain proper operation, a design implementing these Phototriac Couplers should provide at least twice the minimum required triggering current from initial operation.

Recommended Foot Print (reference)

SMT Gullwing Lead-form

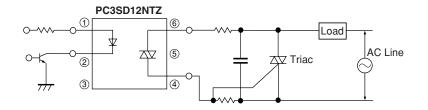
Wide SMT Gullwing Lead-form



(Unit : mm)



• Standard Circuit (Medium/High Power Triac Drive Circuit)



Note) Please add the snubber circuit according to a condition. Any snubber or varistor used for the above mentioned scenarios should be located

as close to the main output triac as possible.

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

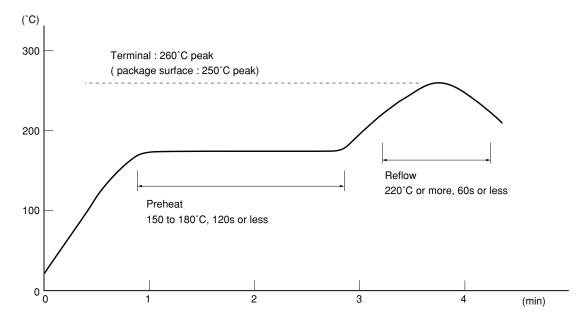


Manufacturing Guidelines

Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below. Soldering should not exceed the curve of temperature profile and time. Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 270°C and within 10s. Preheating is within the bounds of 100 to 150°C and 30 to 80s. Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C. Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



• Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45°C or below. Immersion time should be 3minutes or less.

Ultrasonic cleaning :

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform) Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.



Package specification

• Sleeve package

1. Through-Hole or SMT Gullwing

Package materials

Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

Package method

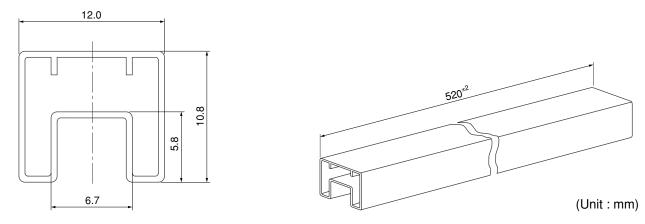
MAX. 50pcs of products shall be packaged in a sleeve.

Both ends shall be closed by tabbed and tabless stoppers.

The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.

MAX. 20 sleeves in one case.

Sleeve outline dimensions



2. Wide Through-Hole or Wide SMT Gullwing

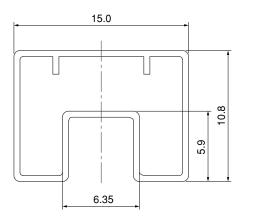
Package materials

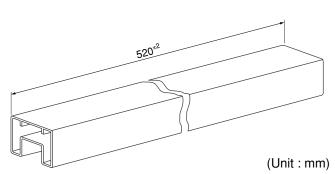
Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

Package method

MAX. 50pcs of products shall be packaged in a sleeve.Both ends shall be closed by tabbed and tabless stoppers.The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.MAX. 20 sleeves in one case.

Sleeve outline dimensions





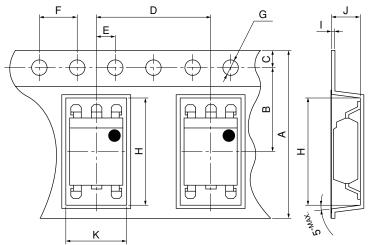


• Tape and Reel package

1. SMT Gullwing

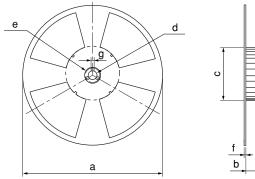
Package materials Carrier tape : A-PET (with anti-static material) Cover tape : PET (three layer system) Reel : PS

Carrier tape structure and Dimensions



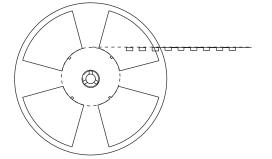
Dimensio	(Unit:mm)					
А	В	C	D	Е	F	G
$16.0^{\pm 0.3}$	$7.5^{\pm0.1}$	$1.75^{\pm 0.1}$	$12.0^{\pm0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5 ^{+0.1}
Н	Ι	J	K			
$10.4^{\pm 0.1}$	$0.4^{\pm 0.05}$	$4.2^{\pm 0.1}$	$7.8^{\pm0.1}$			

Reel structure and Dimensions

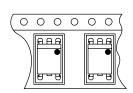


Dimensio	ns List	(Unit : mm)		
а	b	с	d	
330	$17.5^{\pm 1.5}$	100 ^{±1.0}	13 ^{±0.5}	
e	f	g		
23 ^{±1.0}	$2.0^{\pm 0.5}$	$2.0^{\pm 0.5}$		

Direction of product insertion



Pull-out direction



[Packing : 1 000pcs/reel]

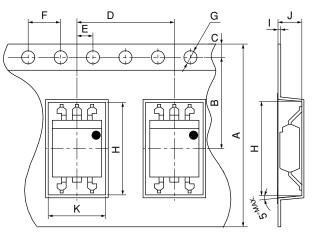


2. Wide SMT Gullwing

Package materials

Carrier tape : A-PET (with anti-static material) Cover tape : PET (three layer system) Reel : PS

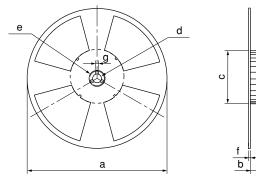
Carrier tape structure and Dimensions



1.1		
I Init	•	mm
Unit		mm)

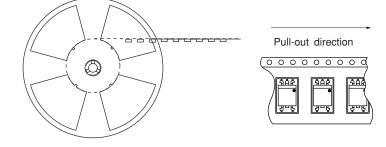
Dimensior	nit : mm)					
А	В	C	D	Е	F	G
24.0 ^{±0.3}	$11.5^{\pm 0.1}$	$1.75^{\pm 0.1}$	$12.0^{\pm0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5 ^{+0.1}
Н	Ι	J	K			
$12.2^{\pm 0.1}$	$0.4^{\pm 0.05}$	$4.15^{\pm0.1}$	$7.6^{\pm 0.1}$			

Reel structure and Dimensions



Dime	ensio	ns List	(Unit : mm)		
	a	b	с	d	
33	30	$25.5^{\pm 1.5}$	$100^{\pm 1.0}$	13 ^{±0.5}	
(e	f	g		
23	±1.0	$2.0^{\pm 0.5}$	$2.0^{\pm 0.5}$		

Direction of product insertion



[Packing: 1 000pcs/reel]

SHARP

Important Notices

• The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.

• Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.

• Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:

(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment [terminal]
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment [trunk lines]
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g., scuba).

• If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Law of Japan, it is necessary to obtain approval to export such SHARP devices.

• This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.

 \cdot Contact and consult with a SHARP representative if there are any questions about the contents of this publication.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Triac & SCR Output Optocouplers category:

Click to view products by Sharp manufacturer:

Other Similar products are found below :

MOC3063S-TA ILD207-X001T ILD615-1X007T VO2223-X001 VO4254H WPPCT-N1066A WPPCT-N1566A WPPCT-Z546D 523170E VO2223A-X007T WPPCT-Z546A WPPCT-Z1046D WPPCT-Z1046A WPPCT-N566D WPPCT-N566A WPPCT-N1566D FODM3053V_NF098 TLP3042SCF VO4258D VO4256D VO4158H-X017T TLP3083(TP1,F MOC3071SM MOC3063STA1-V IL4116-X007 MOC3072SM VO0601-X001T OR-M3052 TLP265J(E(T MOC3020XSM MOC3021X MOC3021XSM MOC3022X MOC3023SR2M MOC3041SM MOC3042XSM MOC3043SR2M MOC3043X MOC3043XSM MOC3052SM MOC3063X MOC3081X MOC3081XSM IS620XSM IS623X VO3062-X007T VO3063-X006 PC3SG21YIZ MOC3020 MOC3020X